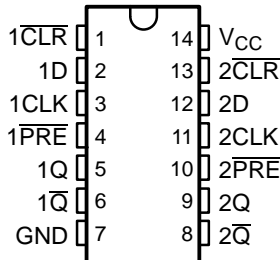


## FEATURES

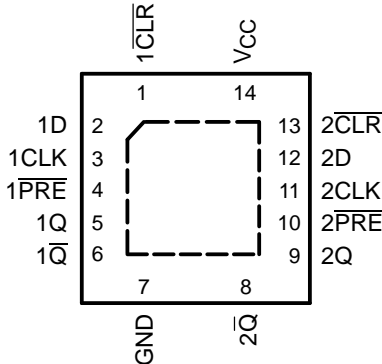
- Operate From 1.65 V to 3.6 V
- Inputs Accept Voltages to 5.5 V
- Max  $t_{pd}$  of 5.2 ns at 3.3 V
- Typical  $V_{OLP}$  (Output Ground Bounce)  
<0.8 V at  $V_{CC} = 3.3$  V,  $T_A = 25^\circ\text{C}$
- Typical  $V_{OHV}$  (Output  $V_{OH}$  Undershoot)  
>2 V at  $V_{CC} = 3.3$  V,  $T_A = 25^\circ\text{C}$

- Latch-Up Performance Exceeds 250 mA Per JESD 17
- ESD Protection Exceeds JESD 22
  - 2000-V Human-Body Model (A114-A)
  - 200-V Machine Model (A115-A)
  - 1000-V Charged-Device Model (C101)

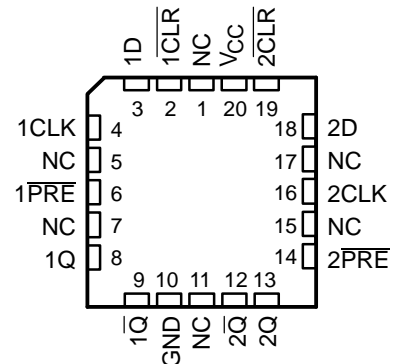
SN54LVC74A . . . J OR W PACKAGE  
SN74LVC74A . . . D, DB, NS, OR PW PACKAGE  
(TOP VIEW)



SN74LVC74A . . . RGY PACKAGE  
(TOP VIEW)



SN54LVC74A . . . FK PACKAGE  
(TOP VIEW)



NC - No internal connection

## DESCRIPTION/ORDERING INFORMATION

The SN54LVC74A dual positive-edge-triggered D-type flip-flop is designed for 2.7-V to 3.6-V  $V_{CC}$  operation, and the SN74LVC74A dual positive-edge-triggered D-type flip-flop is designed for 1.65-V to 3.6-V  $V_{CC}$  operation.

### ORDERING INFORMATION

$T_A$	PACKAGE <sup>(1)</sup>		ORDERABLE PART NUMBER	TOP-SIDE MARKING
–40°C to 85°C	QFN – RGY	Reel of 1000	SN74LVC74ARGYR	LC74A
		Tube of 50	SN74LVC74AD	LVC74A
	SOIC – D	Reel of 2500	SN74LVC74ADR	
		Reel of 250	SN74LVC74ADT	
	SOP – NS	Reel of 2000	SN74LVC74ANSR	LCV74A
	SSOP – DB	Reel of 2000	SN74LVC74ADBR	LC74A
–55°C to 125°C	TSSOP – PW	Tube of 90	SN74LVC74APW	LC74A
		Reel of 2000	SN74LVC74APWR	
		Reel of 250	SN74LVC74APWT	
	CDIP – J	Tube of 25	SNJ54LVC74AJ	SNJ54LVC74AJ
	CFP – W	Tube of 150	SNJ54LVC74AW	SNJ54LVC74AW
	LCCC – FK	Tube of 55	SNJ54LVC74AFK	SNJ54LVC74AFK

(1) Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at [www.ti.com/sc/package](http://www.ti.com/sc/package).



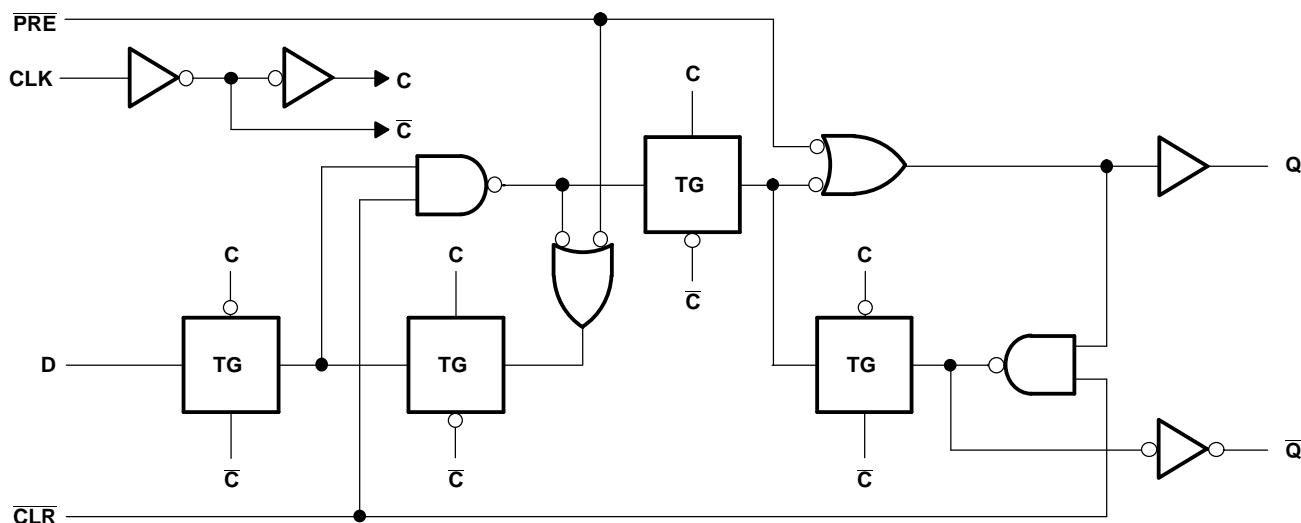
Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

## SCAS287S—JANUARY 1993—REVISED MAY 2005

The data I/Os and control inputs are overvoltage tolerant. This feature allows the use of these devices for down-translation in a mixed-voltage environment.

INPUTS				OUTPUTS	
PRE	CLR	CLK	D	Q	$\bar{Q}$
L	H	X	X	H	L
H	L	X	X	L	H
L	L	X	X	H <sup>(1)</sup>	H <sup>(1)</sup>
H	H	↑	H	H	L
H	H	↑	L	L	H
H	H	L	X	Q <sub>0</sub>	$\bar{Q}_0$

**LOGIC DIAGRAM, EACH FLIP-FLOP  
(POSITIVE LOGIC)**



## Absolute Maximum Ratings<sup>(1)</sup>

over operating free-air temperature range (unless otherwise noted)

			MIN	MAX	UNIT
$V_{CC}$	Supply voltage range		–0.5	6.5	V
$V_I$	Input voltage range <sup>(2)</sup>		–0.5	6.5	V
$V_O$	Output voltage range <sup>(2)(3)</sup>		–0.5	$V_{CC} + 0.5$	V
$I_{IK}$	Input clamp current	$V_I < 0$		–50	mA
$I_{OK}$	Output clamp current	$V_O < 0$		–50	mA
$I_O$	Continuous output current			±50	mA
	Continuous current through $V_{CC}$ or GND			±100	mA
$\theta_{JA}$	Package thermal impedance	D package <sup>(4)</sup>		86	°C/W
		DB package <sup>(4)</sup>		96	
		NS package <sup>(4)</sup>		76	
		PW package <sup>(4)</sup>		113	
		RGY package <sup>(5)</sup>		47	
$T_{stg}$	Storage temperature range		–65	150	°C

- (1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) The input and output negative-voltage ratings may be exceeded if the input and output current ratings are observed.
- (3) The value of  $V_{CC}$  is provided in the recommended operating conditions table.
- (4) The package thermal impedance is calculated in accordance with JESD 51-7.
- (5) The package thermal impedance is calculated in accordance with JESD 51-5.

## Recommended Operating Conditions<sup>(1)</sup>

			SN54LVC74A		SN74LVC74A		UNIT
			MIN	MAX	MIN	MAX	
$V_{CC}$	Supply voltage	Operating	2	3.6	1.65	3.6	V
		Data retention only	1.5		1.5		
$V_{IH}$	High-level input voltage	$V_{CC} = 1.65\text{ V to }1.95\text{ V}$			$0.65 \times V_{CC}$		V
		$V_{CC} = 2.3\text{ V to }2.7\text{ V}$			1.7		
		$V_{CC} = 2.7\text{ V to }3.6\text{ V}$	2		2		
$V_{IL}$	Low-level input voltage	$V_{CC} = 1.65\text{ V to }1.95\text{ V}$			$0.35 \times V_{CC}$		V
		$V_{CC} = 2.3\text{ V to }2.7\text{ V}$			0.7		
		$V_{CC} = 2.7\text{ V to }3.6\text{ V}$		0.8		0.8	
$V_I$	Input voltage		0	5.5	0	5.5	V
$V_O$	Output voltage		0	$V_{CC}$	0	$V_{CC}$	V
$I_{OH}$	High-level output current	$V_{CC} = 1.65\text{ V}$				–4	mA
		$V_{CC} = 2.3\text{ V}$				–8	
		$V_{CC} = 2.7\text{ V}$		–12		–12	
		$V_{CC} = 3\text{ V}$		–24		–24	
$I_{OL}$	Low-level output current	$V_{CC} = 1.65\text{ V}$				4	mA
		$V_{CC} = 2.3\text{ V}$				8	
		$V_{CC} = 2.7\text{ V}$		12		12	
		$V_{CC} = 3\text{ V}$		24		24	
$\Delta t/\Delta v$	Input transition rise or fall rate			10		10	ns/V
$T_A$	Operating free-air temperature		–55	125	–40	85	°C

- (1) All unused inputs of the device must be held at  $V_{CC}$  or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

# SN54LVC74A, SN74LVC74A

## DUAL POSITIVE-EDGE-TRIGGERED D-TYPE FLIP-FLOPS WITH CLEAR AND PRESET

SCAS287S–JANUARY 1993–REVISED MAY 2005



### Electrical Characteristics

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V <sub>CC</sub>	SN54LVC74A			SN74LVC74A			UNIT
			MIN	TYP <sup>(1)</sup>	MAX	MIN	TYP <sup>(1)</sup>	MAX	
V <sub>OH</sub>	I <sub>OH</sub> = −100 μA	1.65 V to 3.6 V				V <sub>CC</sub> − 0.2			V
		2.7 V to 3.6 V	V <sub>CC</sub> − 0.2						
	I <sub>OH</sub> = −4 mA	1.65 V				1.2			
	I <sub>OH</sub> = −8 mA	2.3 V				1.7			
	I <sub>OH</sub> = −12 mA	2.7 V	2.2			2.2			
		3 V	2.4			2.4			
I <sub>OH</sub> = −24 mA	3 V	2.2			2.2				
V <sub>OL</sub>	I <sub>OL</sub> = 100 μA	1.65 V to 3.6 V				0.2			V
		2.7 V to 3.6 V	0.2						
	I <sub>OL</sub> = 4 mA	1.65 V				0.45			
	I <sub>OL</sub> = 8 mA	2.3 V				0.7			
	I <sub>OL</sub> = 12 mA	2.7 V	0.4			0.4			
	I <sub>OL</sub> = 24 mA	3 V	0.55			0.55			
I <sub>I</sub>	V <sub>I</sub> = 5.5 V or GND	3.6 V	±5			±5			μA
I <sub>CC</sub>	V <sub>I</sub> = V <sub>CC</sub> or GND, I <sub>O</sub> = 0	3.6 V	10			10			μA
ΔI <sub>CC</sub>	One input at V <sub>CC</sub> − 0.6 V, Other inputs at V <sub>CC</sub> or GND	2.7 V to 3.6 V	500			500			μA
C <sub>i</sub>	V <sub>I</sub> = V <sub>CC</sub> or GND	3.3 V	5			5			pF

(1) All typical values are at V<sub>CC</sub> = 3.3 V, T<sub>A</sub> = 25°C.

### Timing Requirements

over recommended operating free-air temperature range (unless otherwise noted) (see [Figure 1](#))

			SN54LVC74A				UNIT
			V <sub>CC</sub> = 2.7 V		V <sub>CC</sub> = 3.3 V ± 0.3 V		
			MIN	MAX	MIN	MAX	
f <sub>clock</sub>	Clock frequency		83		100		MHz
t <sub>w</sub>	Pulse duration	PRE or CLR low	3.3		3.3		ns
		CLK high or low	3.3		3.3		
t <sub>su</sub>	Setup time before CLK↑	Data	3.4		3		ns
		PRE or CLR inactive	2.2		2		
t <sub>h</sub>	Hold time, data after CLK↑		1		1		ns

## Timing Requirements

over recommended operating free-air temperature range (unless otherwise noted) (see [Figure 1](#))

			SN74LVC74A								UNIT
			$V_{CC} = 1.8\text{ V}$ $\pm 0.15\text{ V}$		$V_{CC} = 2.5\text{ V}$ $\pm 0.2\text{ V}$		$V_{CC} = 2.7\text{ V}$		$V_{CC} = 3.3\text{ V}$ $\pm 0.3\text{ V}$		
			MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
f <sub>clock</sub>	Clock frequency		83		83		83		150		MHz
t <sub>w</sub>	Pulse duration	$\overline{\text{PRE}}$ or $\overline{\text{CLR}}$ low	4.1		3.3		3.3		3.3		ns
		CLK high or low	4.1		3.3		3.3		3.3		
t <sub>su</sub>	Setup time before CLK↑	Data	3.6		2.3		3.4		3		ns
		$\overline{\text{PRE}}$ or $\overline{\text{CLR}}$ inactive	2.7		1.9		2.2		2		
t <sub>h</sub>	Hold time, data after CLK↑		1		1		1		0		ns

## Switching Characteristics

over recommended operating free-air temperature range (unless otherwise noted) (see [Figure 1](#))

PARAMETER	FROM (INPUT)	TO (OUTPUT)	SN54LVC74A				UNIT
			V <sub>CC</sub> = 2.7 V		V <sub>CC</sub> = 3.3 V ± 0.3 V		
			MIN	MAX	MIN	MAX	
f <sub>max</sub>			83		100		MHz
t <sub>pd</sub>	CLK	Q or $\overline{Q}$	6		1	5.2	ns
	$\overline{\text{PRE}}$ or $\overline{\text{CLR}}$		6.4		1	5.4	

## Switching Characteristics

over recommended operating free-air temperature range (unless otherwise noted) (see [Figure 1](#))

PARAMETER	FROM (INPUT)	TO (OUTPUT)	SN74LVC74A								UNIT
			$V_{CC} = 1.8\text{ V}$ $\pm 0.15\text{ V}$		$V_{CC} = 2.5\text{ V}$ $\pm 0.2\text{ V}$		$V_{CC} = 2.7\text{ V}$		$V_{CC} = 3.3\text{ V}$ $\pm 0.3\text{ V}$		
			MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
$f_{\text{max}}$			83		83		83		150		MHz
$t_{\text{pd}}$	CLK	Q or $\overline{Q}$	1	7.1	1	4.4	1	6	1	5.2	ns
	$\overline{\text{PRE}}$ or $\overline{\text{CLR}}$		1	6.9	1	4.6	1	6.4	1	5.4	
$t_{\text{sk(o)}}$									1		ns

## Operating Characteristics

$T_A = 25^\circ\text{C}$

PARAMETER	TEST CONDITIONS	$V_{CC} = 1.8\text{ V}$	$V_{CC} = 2.5\text{ V}$	$V_{CC} = 3.3\text{ V}$	UNIT
		TYP	TYP	TYP	
$C_{\text{pd}}$	Power dissipation capacitance per flip-flop	f = 10 MHz 24	24	26	pF

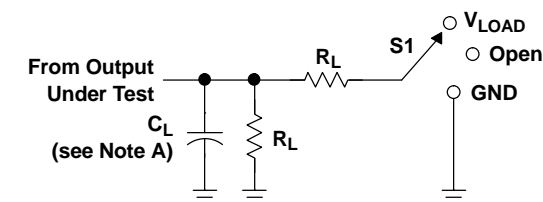
# SN54LVC74A, SN74LVC74A

## DUAL POSITIVE-EDGE-TRIGGERED D-TYPE FLIP-FLOPS

### WITH CLEAR AND PRESET

SCAS287S—JANUARY 1993—REVISED MAY 2005

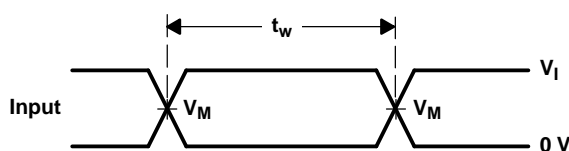
#### PARAMETER MEASUREMENT INFORMATION



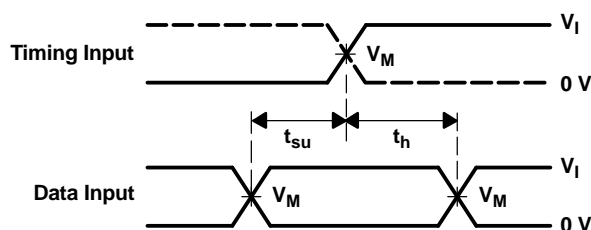
LOAD CIRCUIT

TEST	S1
$t_{PLH}/t_{PHL}$	Open
$t_{PLZ}/t_{PZL}$	$V_{LOAD}$
$t_{PHZ}/t_{PZH}$	GND

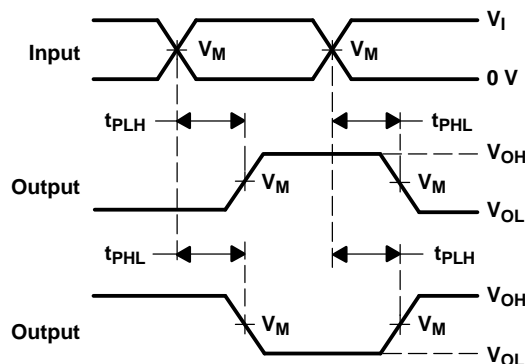
$V_{CC}$	INPUTS		$V_M$	$V_{LOAD}$	$C_L$	$R_L$	$V_{\Delta}$
	$V_I$	$t_r/t_f$					
$1.8\text{ V} \pm 0.15\text{ V}$	$V_{CC}$	$\leq 2\text{ ns}$	$V_{CC}/2$	$2 \times V_{CC}$	30 pF	1 k $\Omega$	0.15 V
$2.5\text{ V} \pm 0.2\text{ V}$	$V_{CC}$	$\leq 2\text{ ns}$	$V_{CC}/2$	$2 \times V_{CC}$	30 pF	500 $\Omega$	0.15 V
2.7 V	2.7 V	$\leq 2.5\text{ ns}$	1.5 V	6 V	50 pF	500 $\Omega$	0.3 V
$3.3\text{ V} \pm 0.3\text{ V}$	2.7 V	$\leq 2.5\text{ ns}$	1.5 V	6 V	50 pF	500 $\Omega$	0.3 V



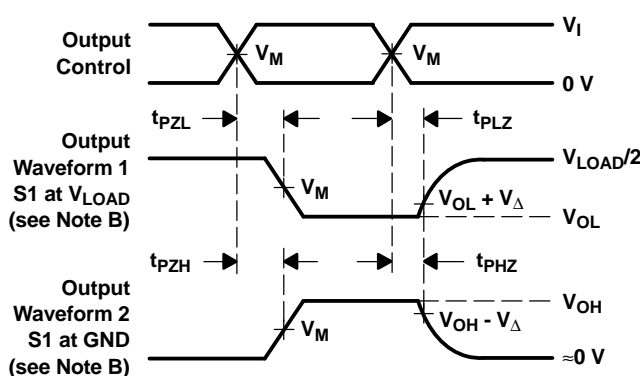
VOLTAGE WAVEFORMS  
PULSE DURATION



VOLTAGE WAVEFORMS  
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS  
PROPAGATION DELAY TIMES  
INVERTING AND NONINVERTING OUTPUTS



VOLTAGE WAVEFORMS  
ENABLE AND DISABLE TIMES  
LOW- AND HIGH-LEVEL ENABLING

- NOTES:
- $C_L$  includes probe and jig capacitance.
  - Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
  - All input pulses are supplied by generators having the following characteristics:  $PRR \leq 10\text{ MHz}$ ,  $Z_O = 50\ \Omega$ .
  - The outputs are measured one at a time, with one transition per measurement.
  - $t_{PLZ}$  and  $t_{PHZ}$  are the same as  $t_{dis}$ .
  - $t_{PZL}$  and  $t_{PZH}$  are the same as  $t_{en}$ .
  - $t_{PLH}$  and  $t_{PHL}$  are the same as  $t_{pd}$ .
  - All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms

**PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
5962-9761601Q2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
5962-9761601QCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type
5962-9761601QDA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type
5962-9761601V2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
5962-9761601VCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type
5962-9761601VDA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type
SN74LVC74AD	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC74ADBLE	OBSOLETE	SSOP	DB	14		TBD	Call TI	Call TI
SN74LVC74ADBR	ACTIVE	SSOP	DB	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC74ADBRG4	ACTIVE	SSOP	DB	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC74ADE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC74ADG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC74ADR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC74ADRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC74ADRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC74ADT	ACTIVE	SOIC	D	14	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC74ADTE4	ACTIVE	SOIC	D	14	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC74ADTG4	ACTIVE	SOIC	D	14	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC74ANSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC74ANSRG4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC74APW	ACTIVE	TSSOP	PW	14	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC74APWE4	ACTIVE	TSSOP	PW	14	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC74APWG4	ACTIVE	TSSOP	PW	14	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC74APWLE	OBSOLETE	TSSOP	PW	14		TBD	Call TI	Call TI
SN74LVC74APWR	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC74APWRE4	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC74APWRG3	PREVIEW	TSSOP	PW	14	2000	TBD	Call TI	Call TI
SN74LVC74APWRG4	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC74APWT	ACTIVE	TSSOP	PW	14	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
no Sb/Br)								
SN74LVC74APWTE4	ACTIVE	TSSOP	PW	14	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC74APWTG4	ACTIVE	TSSOP	PW	14	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC74ARGYR	ACTIVE	VQFN	RGY	14	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
SN74LVC74ARGYRG4	ACTIVE	VQFN	RGY	14	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
SNJ54LVC74AFK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
SNJ54LVC74AJ	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type
SNJ54LVC74AW	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type

<sup>(1)</sup> The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

<sup>(2)</sup> Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

<sup>(3)</sup> MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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## OTHER QUALIFIED VERSIONS OF SN54LVC74A, SN54LVC74A-SP, SN74LVC74A :

- Automotive: [SN74LVC74A-Q1](#)
- Enhanced Product: [SN74LVC74A-EP](#)

NOTE: Qualified Version Definitions:

- Automotive - Q100 devices qualified for high-reliability automotive applications targeting zero defects
- Enhanced Product - Supports Defense, Aerospace and Medical Applications



**TAPE AND REEL INFORMATION**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LVC74ADBR	SSOP	DB	14	2000	330.0	16.4	8.2	6.6	2.5	12.0	16.0	Q1
SN74LVC74ADR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN74LVC74ANSR	SO	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
SN74LVC74APWR	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
SN74LVC74ARGYR	VQFN	RGY	14	3000	330.0	12.4	3.75	3.75	1.15	8.0	12.0	Q1

## TAPE AND REEL BOX DIMENSIONS



\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LVC74ADBR	SSOP	DB	14	2000	346.0	346.0	33.0
SN74LVC74ADR	SOIC	D	14	2500	346.0	346.0	33.0
SN74LVC74ANSR	SO	NS	14	2000	346.0	346.0	33.0
SN74LVC74APWR	TSSOP	PW	14	2000	346.0	346.0	29.0
SN74LVC74ARGYR	VQFN	RGY	14	3000	346.0	346.0	29.0

J (R-GDIP-T\*\*)

14 LEADS SHOWN

# CERAMIC DUAL IN-LINE PACKAGE



PINS ** DIM	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)



4040083/F 03/03

- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. This package is hermetically sealed with a ceramic lid using glass frit.
  - D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
  - E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

W (R-GDFP-F14)

CERAMIC DUAL FLATPACK



- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. This package can be hermetically sealed with a ceramic lid using glass frit.
  - D. Index point is provided on cap for terminal identification only.
  - E. Falls within MIL STD 1835 GDFP1-F14 and JEDEC MO-092AB

## FK (S-CQCC-N\*\*)

## LEADLESS CERAMIC CHIP CARRIER

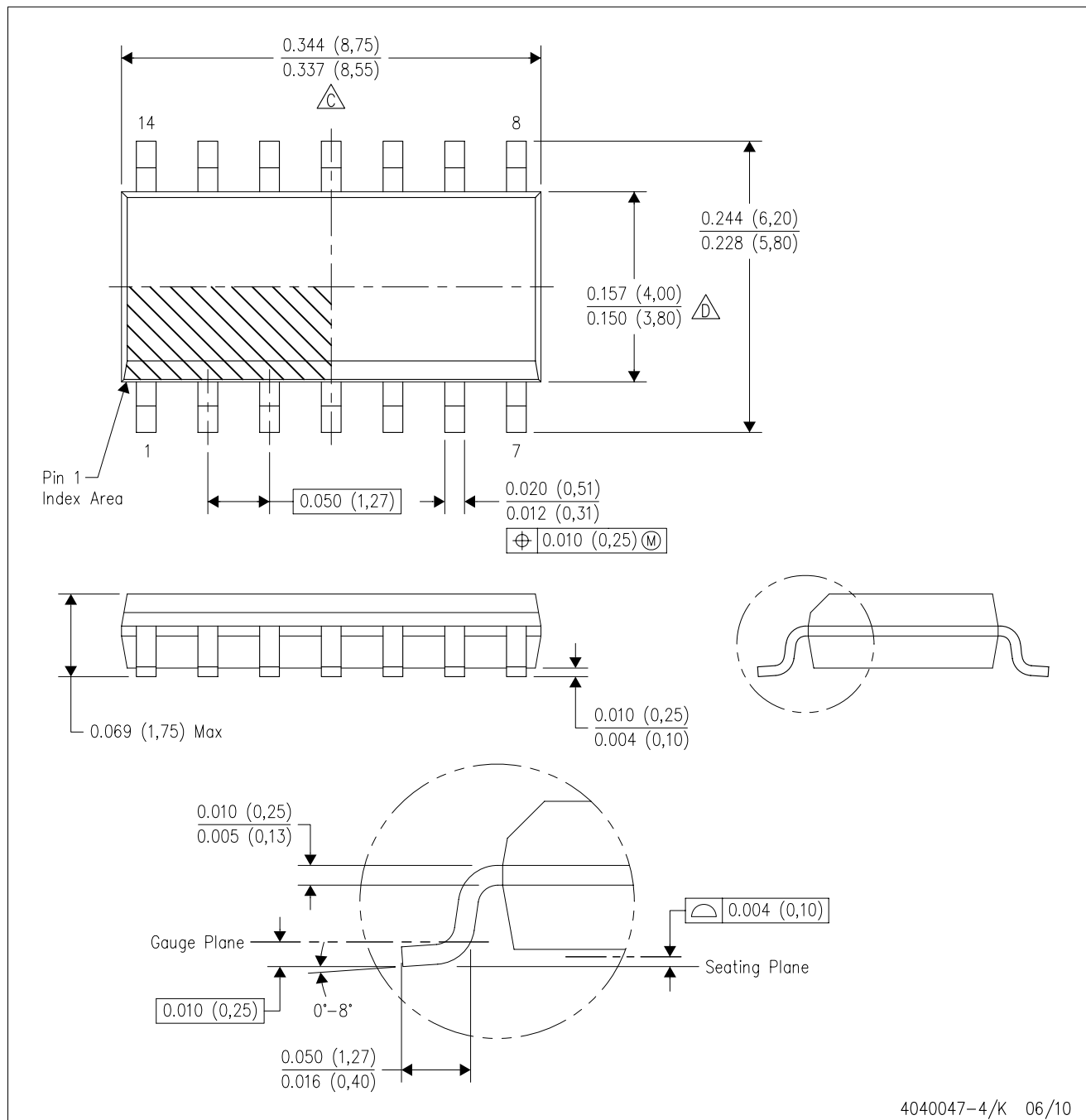
28 TERMINAL SHOWN



- NOTES:
- All linear dimensions are in inches (millimeters).
  - This drawing is subject to change without notice.
  - This package can be hermetically sealed with a metal lid.
  - The terminals are gold plated.
  - Falls within JEDEC MS-004

D (R-PDSO-G14)

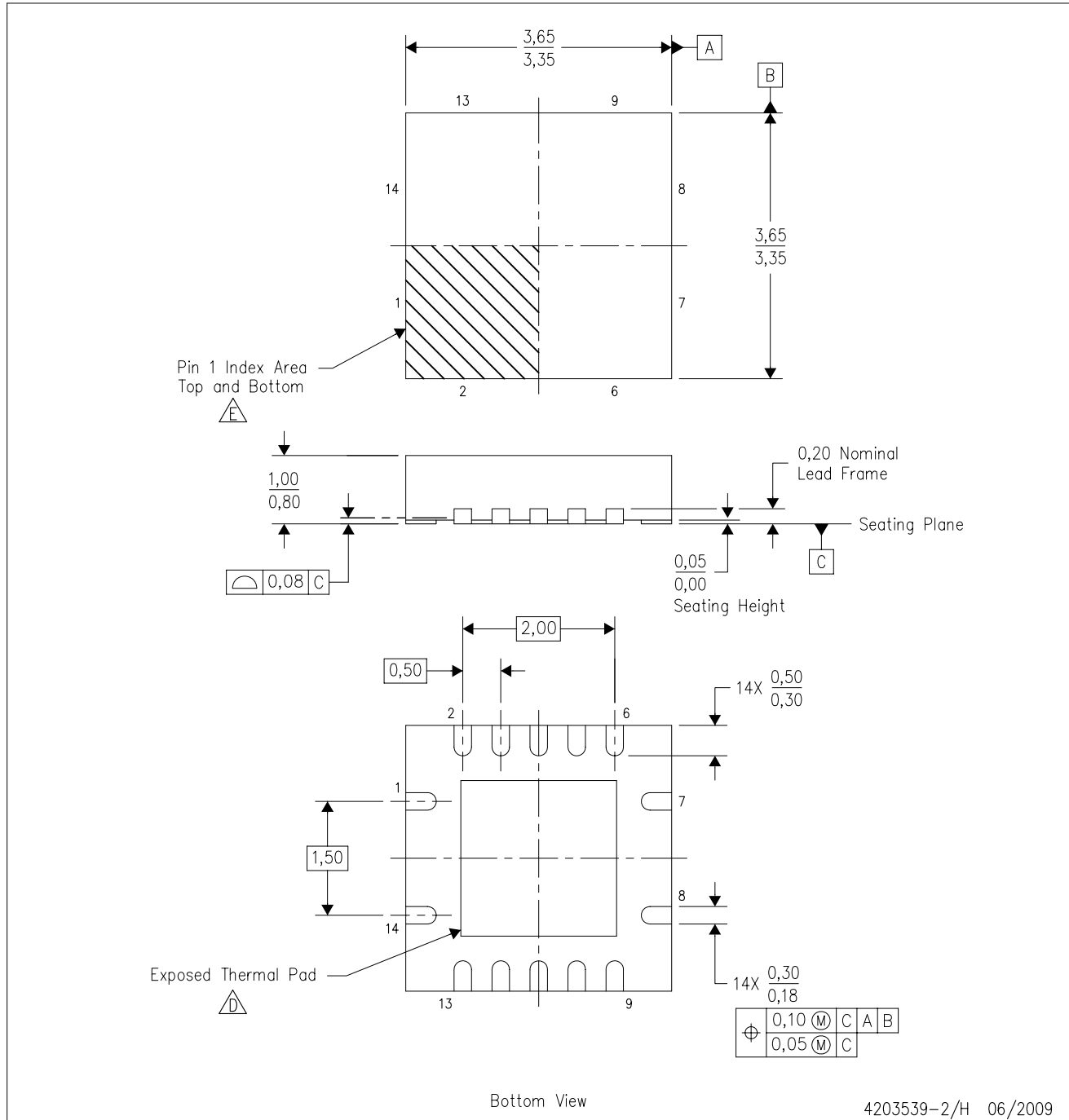
PLASTIC SMALL-OUTLINE PACKAGE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 (0,15) per end.
  - D. Body width does not include interlead flash. Interlead flash shall not exceed .017 (0,43) per side.
  - E. Reference JEDEC MS-012 variation AB.

RGY (S-PVQFN-N14)

PLASTIC QUAD FLATPACK NO-LEAD



4203539-2/H 06/2009

- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
  - B. This drawing is subject to change without notice.
  - C. QFN (Quad Flatpack No-Lead) package configuration.
  - The package thermal pad must be soldered to the board for thermal and mechanical performance. See the Product Data Sheet for details regarding the exposed thermal pad dimensions.
  - Pin 1 identifiers are located on both top and bottom of the package and within the zone indicated. The Pin 1 identifiers are either a molded, marked, or metal feature.
  - F. Package complies to JEDEC MO-241 variation BA.

# MECHANICAL DATA

NS (R-PDSO-G\*\*)

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN



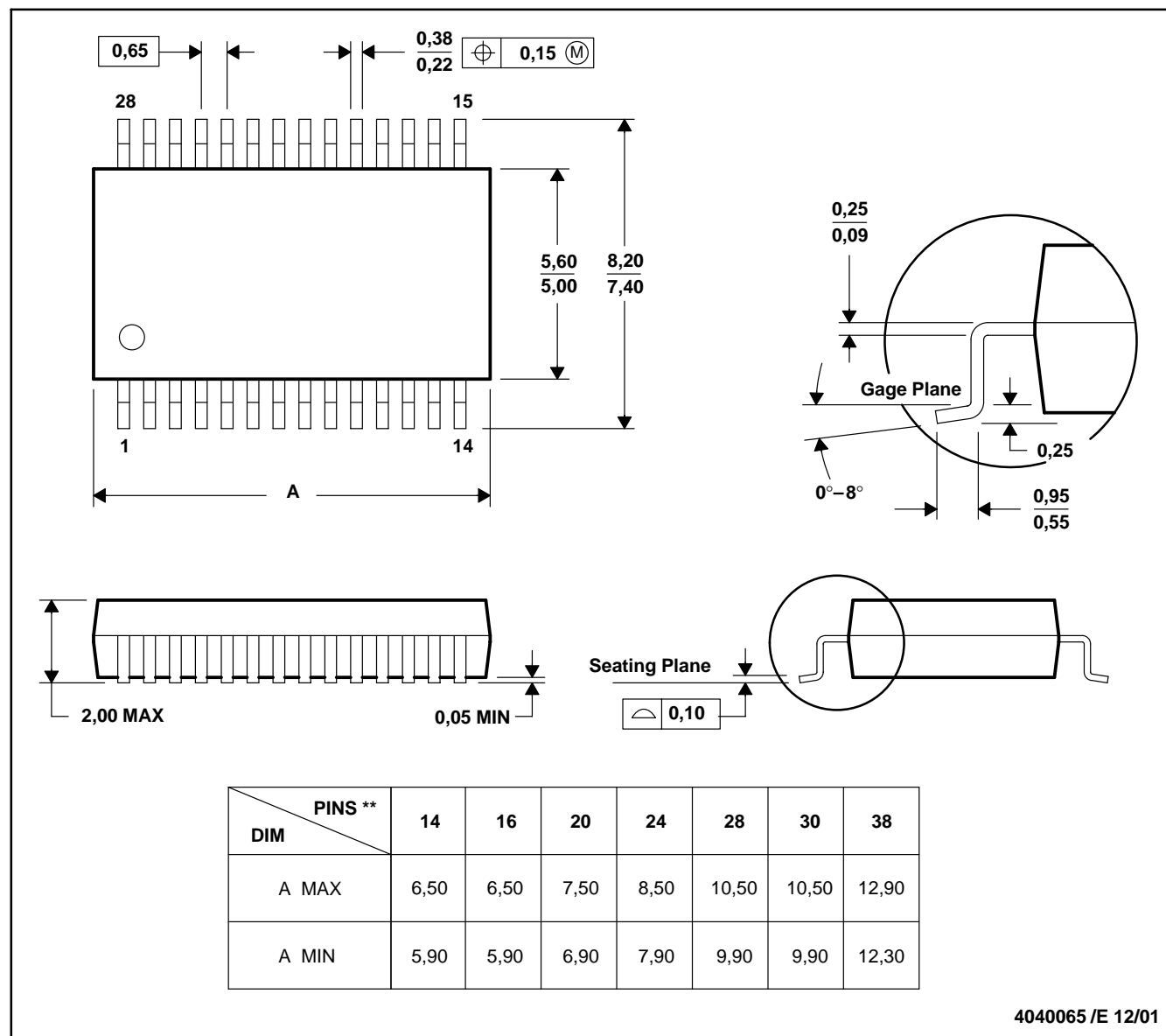
- NOTES:
- All linear dimensions are in millimeters.
  - This drawing is subject to change without notice.
  - Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



## DB (R-PDSO-G\*\*)

## PLASTIC SMALL-OUTLINE

28 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.  
 B. This drawing is subject to change without notice.  
 C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.  
 D. Falls within JEDEC MO-150

## PW (R-PDSO-G\*\*)

## PLASTIC SMALL-OUTLINE PACKAGE

14 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.  
 B. This drawing is subject to change without notice.  
 C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.  
 D. Falls within JEDEC MO-153

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Interface	<a href="http://interface.ti.com">interface.ti.com</a>	Energy	<a href="http://www.ti.com/energy">www.ti.com/energy</a>
Logic	<a href="http://logic.ti.com">logic.ti.com</a>	Industrial	<a href="http://www.ti.com/industrial">www.ti.com/industrial</a>
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Microcontrollers	<a href="http://microcontroller.ti.com">microcontroller.ti.com</a>	Security	<a href="http://www.ti.com/security">www.ti.com/security</a>
RFID	<a href="http://www.ti-rfid.com">www.ti-rfid.com</a>	Space, Avionics & Defense	<a href="http://www.ti.com/space-avionics-defense">www.ti.com/space-avionics-defense</a>
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#### Как с нами связаться

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